

EAST Search History

EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1338822	(clean or cleaning or cleaned or cleanse or cleansed or cleansing or cleanser or wash or washing or washed or rinse or rinsing or rinsed or treat or treated or treatment or treating or dry or drying or dried or process or processing or processed) with (semiconductor or wafer or silicon or substrate)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/27 09:26
L2	3509	("DIW" or water or "H2O" or "H.sub.2O" or fluid or liquid) with (nitrogen or "N2" or "N.sub.2" or gas or gaseous or (inactive or inert) near4 gas or vapor or vapour or vaporous or vapourous) with (nozzle or dispenser or jet or jetted or jetting) same (move or moving or movement or moved or translat\$4)	USPAT	OR	ON	2010/01/27 09:33
L4	162	I1 same I2	USPAT	OR	ON	2010/01/27 11:04
L5	231223	(dry or drying or dried) with (semiconductor or wafer or silicon or substrate)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/27 11:05
L6	122	I4 and I5	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/27 11:05
L7	362629	("134"/\$ or "34"/\$ or "438"/\$).ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/27 11:05

L8	87	l6 and l7	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/27 11:05
L9	776166	(move or moving or moved or transvers\$4 or translat\$4) same (center or radial or radially or middle or radius or central or centrally) same (peripher\$ or edge or end adj3 face outward or bevel \$ or outer adj3 (edge or boundary))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/27 11:51
L10	904738	(move or moving or moved or transvers\$4 or translat\$4 or movement) same (center or radial or radially or middle or radius or central or centrally) same (peripher\$ or edge or end adj3 face outward or bevel\$ or outer adj3 (edge or boundary))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/27 11:52
S1	1186	ohnno-h\$.in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/25 16:40
S2	1840	sekiguchi-k	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/25 16:41
S3	4572	sekiguchi-k\$.in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/25 16:41
S4	5736	S1 or S3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/25 16:41

S5	255310	(clean or cleaning or cleaned or cleanse or cleansed or cleansing or cleanser or wash or washing or washed or rinse or rinsing or rinsed or treat or treated or treatment or treating) with (semiconductor or wafer or silicon)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/25 16:43
S6	466	(nozzle or jet or jetted) with (move or moving or moved or transvers\$4) with (center or radial or radially) with (peripher\$ or edge or end adj3 face) same (gas or nitrogen or "N2" or "N.sub.2" or inert adj gas)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/25 16:59
S7	2	"20060048792".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/25 17:00
S8	2	"5882433".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/25 17:01
S9	2	"20040074526".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/25 17:04
S10	2	"20030192577".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/25 19:43
S11	2	"20060042722".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/25 19:48
S12	2	"5997653".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/25 19:49

S13	2	"6589359".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/25 19:50
S14	2	"6770151".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/25 19:54
S15	1338315	(clean or cleaning or cleaned or cleanse or cleansed or cleansing or cleanser or wash or washing or washed or rinse or rinsing or rinsed or treat or treated or treatment or treating or dry or drying or dried or process or processing or processed) with (semiconductor or wafer or silicon or substrate)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/25 20:18
S16	660	(nozzle or jet or jetted or spray or spraying or sprayed or jetting) with (move or moving or moved or transvers\$4) with (center or radial or radially or central or middle) with (peripher\$ or edge or end adj3 face) same (gas or nitrogen or "N2" or "N.sub.2" or inert adj gas or inactive adj3 gas or surface adj3 tension)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/25 20:19
S17	301864	("134"/\$ or "438"/\$).ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/25 20:19
S18	174	S15 and S16	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/25 20:24

S19	86	S18 and S17	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/25 20:24
S20	0	("2008/0251101").URPN.	USPAT	OR	ON	2010/01/25 20:37
S21	0	("2008/0251101").URPN.	USPAT	OR	ON	2010/01/25 20:37
S22	0	("2008/0251101").URPN.	USPAT	OR	ON	2010/01/25 20:37
S23	0	("2007/0246079").URPN.	USPAT	OR	ON	2010/01/25 22:30
S24	0	"20030079764".pn.	USPAT	OR	ON	2010/01/25 22:51
S25	1	"20030079764".pn.	US-PGPUB; USPAT	OR	ON	2010/01/25 22:51
S26	1	"20040040177".pn.	US-PGPUB; USPAT	OR	ON	2010/01/25 22:55
S27	1338822	(clean or cleaning or cleaned or cleanse or cleansed or cleansing or cleanser or wash or washing or washed or rinse or rinsing or rinsed or treat or treated or treatment or treating or dry or drying or dried or process or processing or processed) with (semiconductor or wafer or silicon or substrate)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/26 20:19
S28	1494	(nozzle or jet or jetted or spray or spraying or sprayed or jetting) with (move or moving or moved or transvers\$4 or translat\$ or movement) with (center or radial or radially or central or middle) same (peripher\$ or edge or end adj3 face) same (gas or nitrogen or "N2" or "N.sub.2" or inert adj gas or inactive adj3 gas or surface adj3 tension)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/26 20:21

S29	117831	("134"/\$ or "34"/\$).ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/26 20:22
S30	154	S27 same S28	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/26 20:22
S31	73	S30 and S29	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/26 20:22
S32	0	("2009/0202951").URPN.	USPAT	OR	ON	2010/01/26 20:24
S33	7	("4027686" "4871417" "5248380" "5351360" "5372652" "5456758" "5558110").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/01/26 20:39
S34	92	("5997653").URPN.	USPAT	OR	ON	2010/01/26 20:39
S35	362629	("134"/\$ or "34"/\$ or "438"/\$).ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/26 20:52
S36	2800	(nozzle or jet or jetted or stream\$) with (move or moving or moved or transvers\$4 or translat\$4) same (center or radial or radially or middle or radius) same (peripher\$ or edge or end adj3 face outward or bevel\$ or outer adj3 (edge or boundary)) same (gas or nitrogen or "N2" or "N.sub.2" or inert adj gas or gaseous or vapor or vapour or vaporous or vapourous or inactive adj3 (gas or gaseous)) same (liquid or fluid or rinse or water or "H2O" or "H.sub.2O")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/26 20:53

S37	3539	(nozzle or jet or jetted or stream\$) with (move or moving or moved or transvers\$4 or translat\$4) same (center or radial or radially or middle or radius or central or centrally) same (peripher\$ or edge or end adj3 face outward or bevel\$ or outer adj3 (edge or boundary)) same (gas or nitrogen or "N2" or "N.sub.2" or inert adj gas or gaseous or vapor or vapour or vaporous or vapourous or inactive adj3 (gas or gaseous)) same (liquid or fluid or rinse or water or "H2O" or "H.sub.2O")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/26 20:53
S38	247	S37 and S29	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/26 20:54
S39	1338822	(clean or cleaning or cleaned or cleanse or cleansed or cleansing or cleanser or wash or washing or washed or rinse or rinsing or rinsed or treat or treated or treatment or treating or dry or drying or dried or process or processing or processed) with (semiconductor or wafer or silicon or substrate)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/26 20:54
S40	4219	(nozzle or jet or jetted or stream\$) with (move or moving or moved or transvers\$4 or translat\$4 or movement) same (center or radial or radially or middle or radius or central or centrally) same (peripher\$ or edge or end adj3 face outward or bevel\$ or outer adj3 (edge or boundary)) same (gas or nitrogen or "N2" or "N.sub.2" or inert adj gas or gaseous or vapor or vapour or vaporous or vapourous or inactive adj3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/26 20:55

		(gas or gaseous)) same (liquid or fluid or rinse or water or "H2O" or "H.sub.2O")				
S41	255938	(two or second or multiple or many or plural or plurality) near4 (nozzle or jet or jetted or jetting or sprayer or dispenser)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/26 20:56
S42	175	S39 same S40	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/26 20:56
S43	130	S42 and S41	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/26 20:56
S44	88	S43 and S35	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/26 20:57
S45	2	"20030172995".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/26 21:12
S46	2	"20030172955".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/26 21:12
S47	0	("2006/0108068").URPN.	USPAT	OR	ON	2010/01/26 21:19
S48	3509	("DIW" or water or "H2O" or "H.sub.2O" or fluid or liquid) with (nitrogen or "N2" or "N.sub.2" or gas or gaseous or (inactive or inert) near4 gas or vapor or vapour or vaporous or vapourous) with (nozzle or dispenser or jet or jetted or jetting) same (move or moving or movement or moved or translat\$4)	USPAT	OR	ON	2010/01/26 23:35

S49	162	S39 same S48	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/26 23:35
S50	101	S49 and S35	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/26 23:35
S51	85	S50 not S44	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/26 23:36
S52	231223	(dry or drying or dried) with (semiconductor or wafer or silicon or substrate)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/26 23:36
S53	71	S51 and S52	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/01/26 23:36

EAST Search History (Interference)

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